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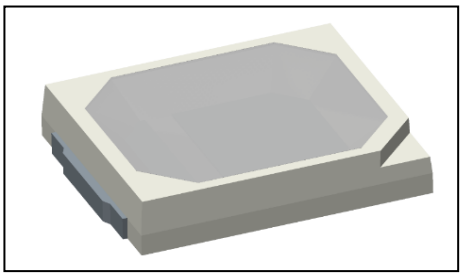
4.1 Handling Precautions 产品使用注意事项

1. Description 产品介绍

1.1General Description 产品描述



The Far Red source color devices are made with AlGaAs on Substrate Light Emitting Diode.

Product package 2.8mmX3.5mmX0.65mm

远红光LED由AlGaAs三种元素芯片激发而成，产品尺寸：2.8mmX3.5mmX0.65mm

1.2Features 产品特征

PLCC Package.PLCC封装

Extremely wide viewing angle.发光角度大

Suitable for all SMT assembly and solder process.适用于所有的SMT组装和焊接工艺

Available on tape and reel.适用于载带及卷轴

Moisture sensitivity level: Level 3.防潮等级 Level 3

RoHS compliant.满足RoHS要求

1. 产品应用

Plant factory.植物工厂

Tissue culture.组织培养

Landscape lighting.景观照明等

General use.其他通用应用

1.4Package Dimension 封装尺寸

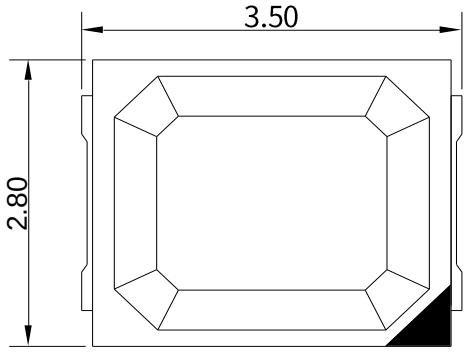


Fig.1-1 Top view 正面视图

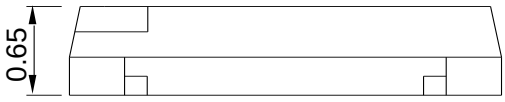


Fig.1-2Side view 侧面视图

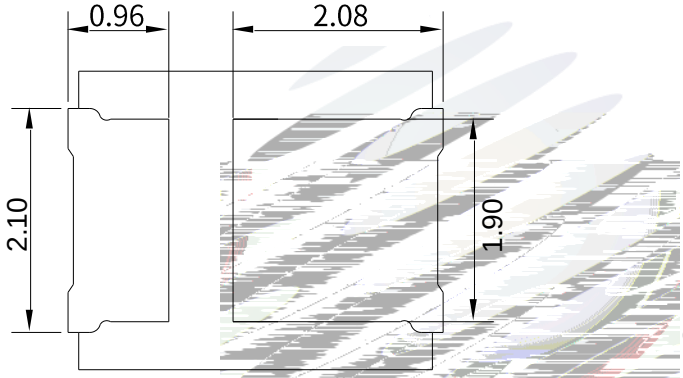


Fig.1-3Bottom view 背面视图

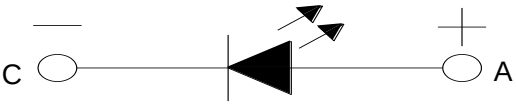


Fig.1-4Polarity 极性

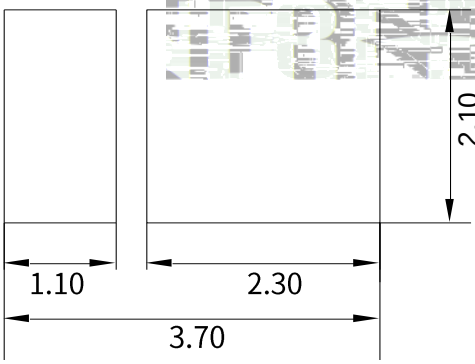


Fig.1-5Soldering patterns 推荐焊盘

Notes 备注:

1. All dimensions units are millimeters. 所有尺寸标注单位为毫米
2. All dimensions tolerances are ±0.2mm unless otherwise noted. ±0.2 毫米

Junction Temperature （结温）	T_J	115	

Notes 备注：

1. 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms,占空比1/10.

2. The above forward voltage measurement allowance tolerance is ±0.1V. 以上所示电压测量误差 ±0.1V.

3. The above wavelength measurement allowance tolerance is 1nm. 以上所示波长测量误差 ±1nm.

4. The above Total radiant flux measurement allowance tolerance ±10%. 上述辐射功率的测试允许公差为±10%.

5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product. 使用功率不能超过规定的最大值。

6. All measurements were made under the standardized environment of Refond. 所有测试都是基于瑞丰现有的标准测试平台。

7.When the LEDs are in operation the maximum current should be decided after measuring the package temperature，junction temperature should not exceed the maximum rate. LED 使用的最大电流需要根据散热条件确定，结温不能超过最大值。

1.6 Bin Range Of Forward Voltage and Total radiant flux and Peak wavelength (IF=150mA)电压与辐射通量与峰值波长分 BIN 范围(IF=150mA)

Table 1-3

V_F V	B1	B2	C1	C2	D1	D2	E1	E2
	1.8-1.9	1.9-2.0	2.0-2.1	2.1-2.2	2.2-2.3	2.3-2.4	2.4-2.5	2.5-2.6
RF-AL-T28352H0FR-00	R25	R26	/	/	/	/	/	/
$_p$	730-735	735-740	/	/	/	/	/	/
RF-AL-T28352H0FR-00	FR	FR2	/	/	/	/	/	/
$_e$ mW	40-90	90-140	/	/	/	/	/	/

1.7 Typical optical characteristics curves 典型光学特性曲线

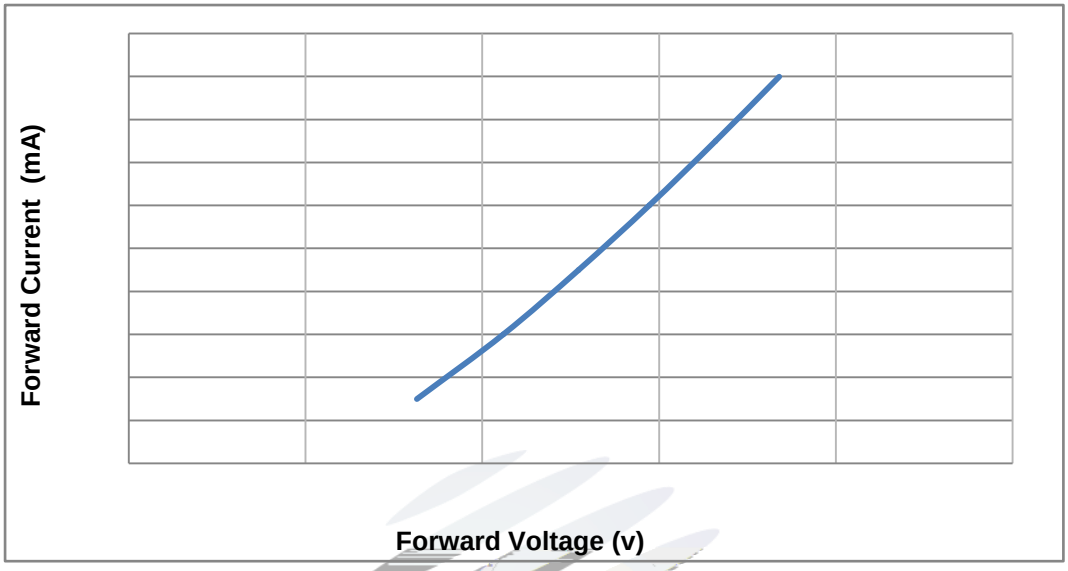


Fig 1-7 Forward Voltage Vs. Forward Current伏安特性曲线

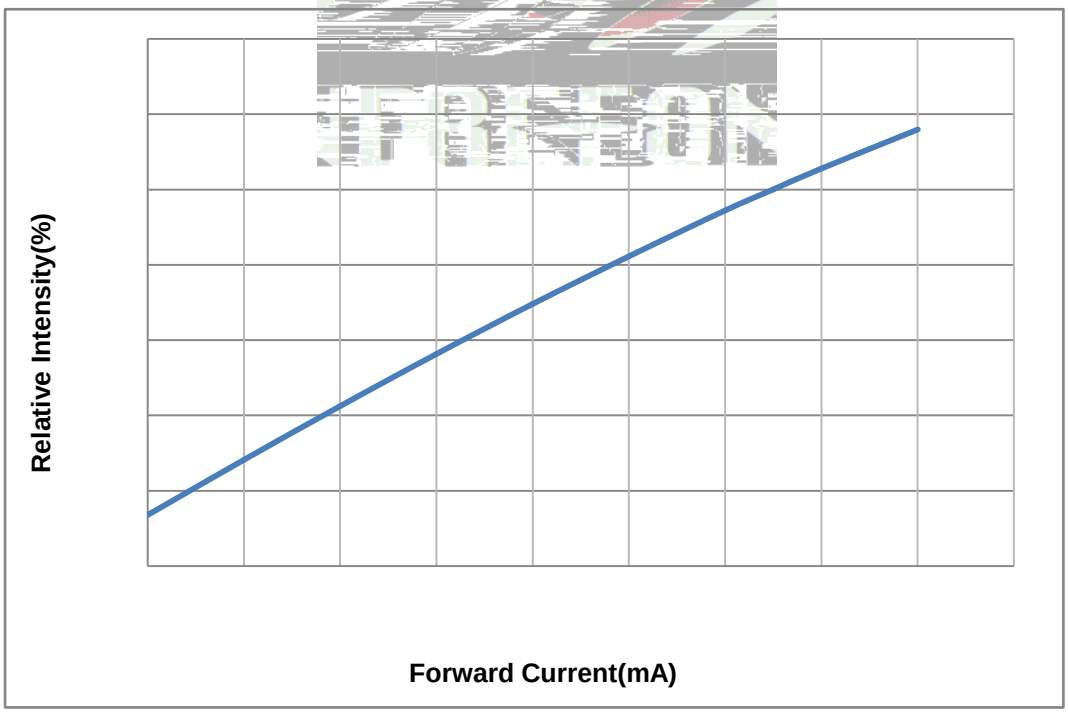


Fig 1-8 Forward Current Vs. Relative Intensity正向电流与相对光强特性曲线

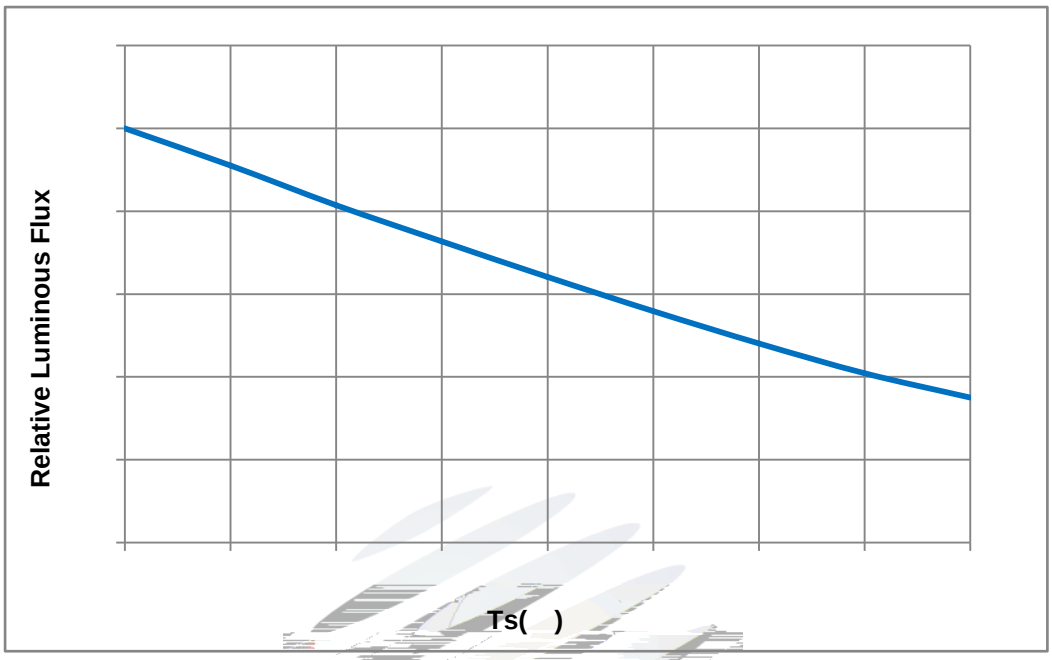


Fig 1-9 Solder Temperature Vs Relative Intensity管脚温度与相对光强特性曲线

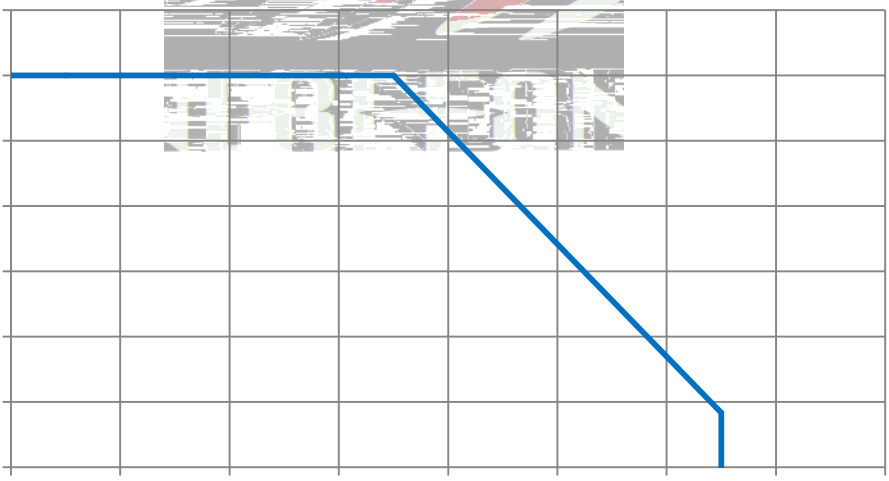


Fig 1-10 Solder Temperature VsForward Current管脚温度与正向电流特性曲线

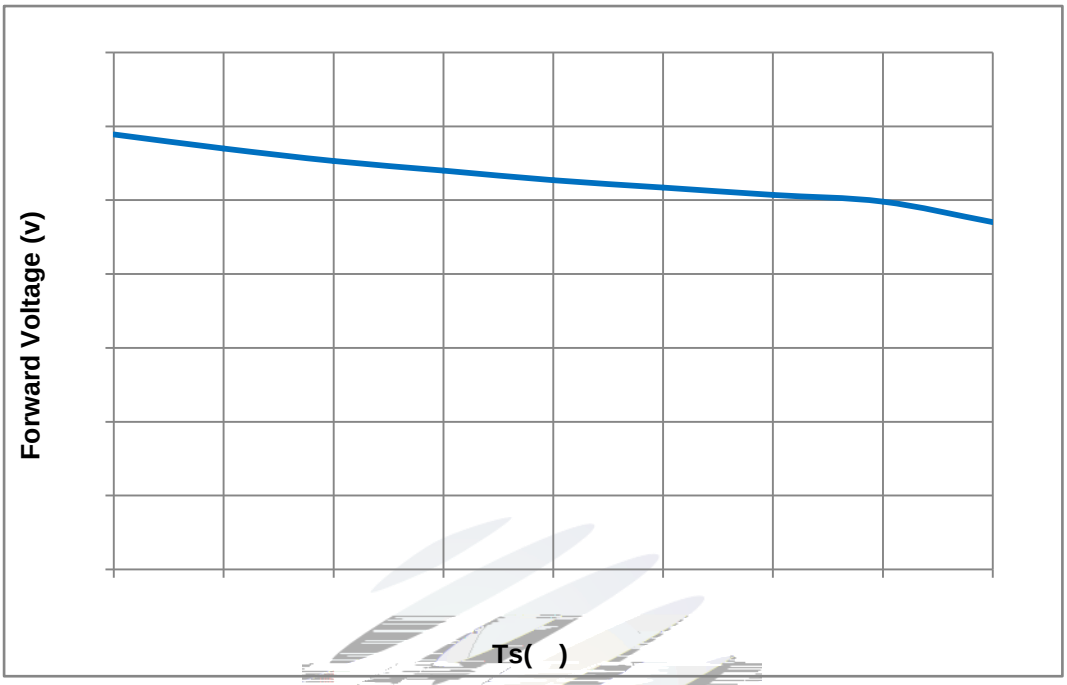


Fig 1-11 Forward Voltage Vs Solder Temperature电压与管脚温度特性曲线

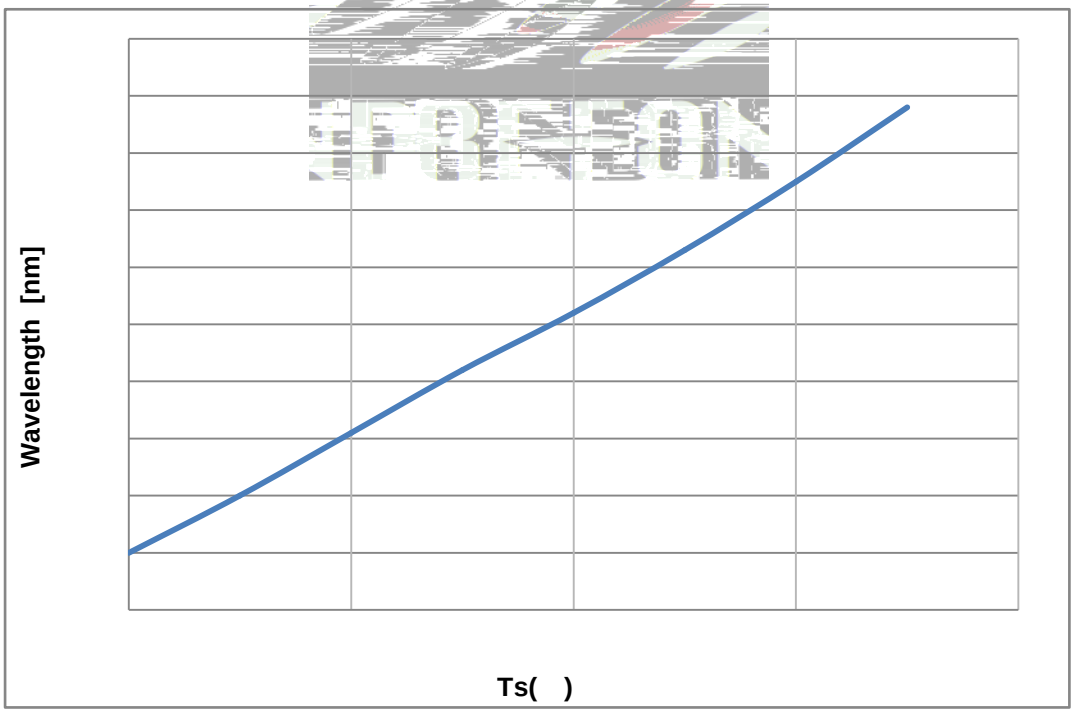


Fig 1-12 Wavelength Vs. Pin Temperature波长与引脚温度特性曲线

2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package:Max 4000pcs/reel.包装每卷最多 4000pcs。

2.1.1Carrier Tape Dimension 载带尺寸

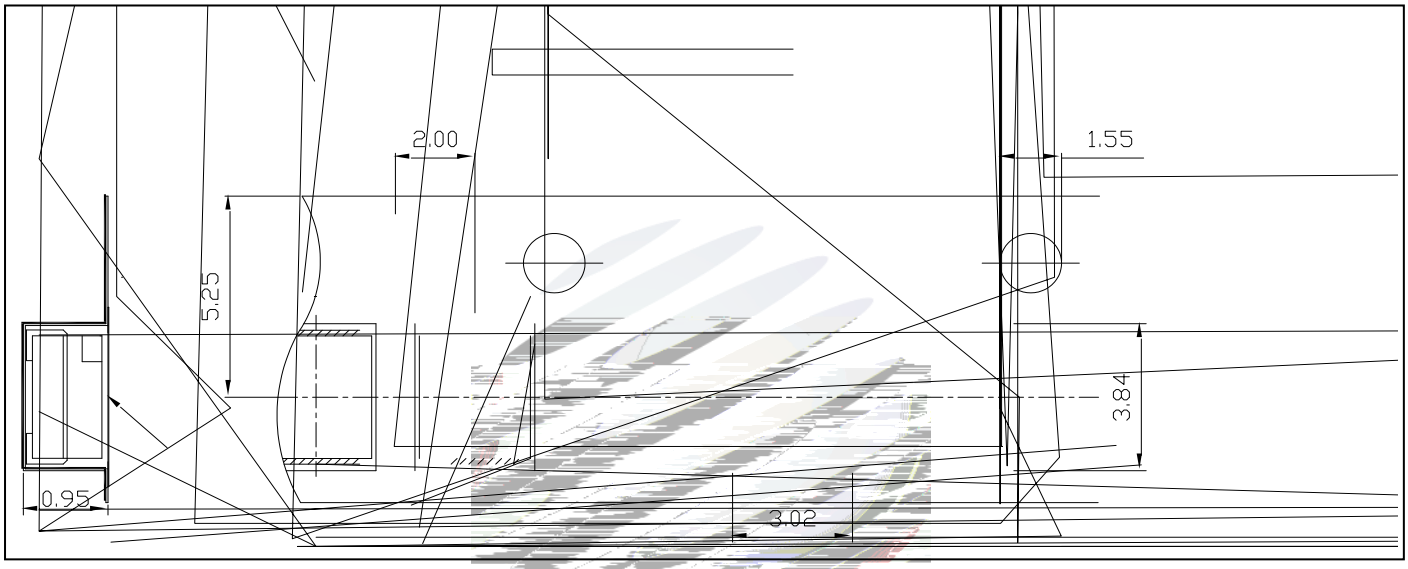


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2Reel Dimension 卷盘尺寸

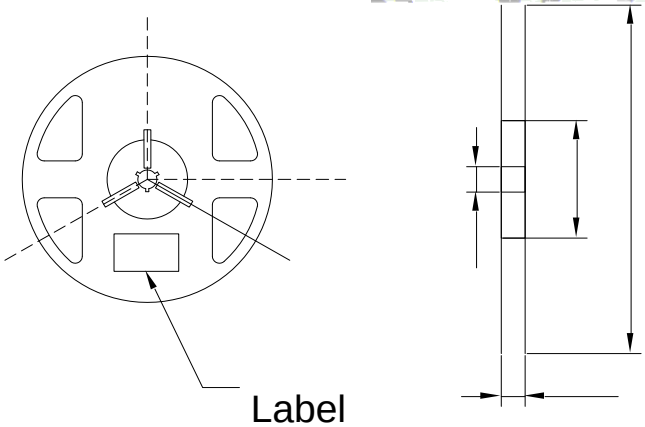


Fig.2-2 Reel 卷盘

Table 2-1 Reel Dimension 卷盘尺寸

A	10.5±0.5mm
B	178±1mm
C	59±1mm
D	13.5±0.5mm

Notes 备注:

The tolerances unless mentioned ±0.1mm. Unit : mm注：未注公差为±0.1毫米，尺寸单位：毫米。

2.1.3Label Form Specification 标签规格

PART NO.
SPEC NO.
LOT NO.
BIN CODE
e WLP
V_F
QTY:
DATE:

Fig 2-3 Label Form 标签模板

Table 2-2 Label Form Specification 标签规格

PART NO.	Part Number 品名
SPEC NO.	Spec Number 规格
LOT NO.	Lot Number 批次号
BIN CODE	Bin Code 参数代码
e	Radiation flux 辐射功率
V_F	Forward Voltage 正向电压
WLP	Wavelength 波长代码
QTY	Packing Quantity 数量
DATE	Made Date 生产日期

2.2Moisture Resistant Packing 防潮包装

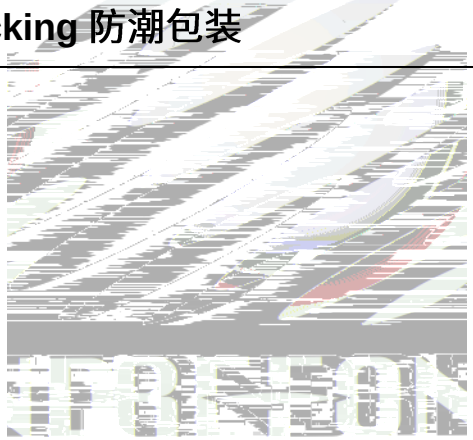


Fig.2-4 Packing specification 包装说明

2.3Cardboard Box 包装纸箱

Fig.2-5 Cardboard Box 包装纸箱 e

2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-2 Test items and conditions 测试项目及条件

TestItems 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260℃max T=10 sec	2times	10pcs.	0/1
Thermal Shock 冷热冲击	JESD22-A106	-40℃ 15min 10s 100℃ 15min	100 cycle	10pcs.	0/1
High Temperature Storage 高温保存	JESD22-A103	Temp:100℃	1000hrs.	10pcs.	0/1
Low Temperature Storage 低温保存	JESD22-A119	Temp:-40℃	1000hrs.	10pcs.	0/1
Life Test 常温测试	JESD22-A108	Ta=25℃ I_F=150mA	1000hrs.	10pcs.	0/1
High Temperature High Humidity Life Test 高温高湿测试	JESD22-A101	60℃/ 90%R_H I_F=150mA	1000hrs.	10pcs.	0/1

2.5 Criteria For Judging Damage 失效判定标准

Table 2-3 Criteria for judging damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	Applicable project 适用项目
Forward Voltage 电压	V_F	I_F=150mA	≤±10%	Reflow Thermal Shock High and Low Temperature Storage Life Test
Luminous Intensity 光强	I_V	I_F=150mA	Maintenance≥70% 光强维持率	
Lamp Bead Light Test 灯珠点亮测试	/	I_F=150mA	No open circuit short circuit or flicke 无开路、短路、闪变	High Temperature High Humidity Life Test

Notes 备注：

1.U.S.L: Upper standard level 规格上限 L.S.L: Lower standard level 规格下限

2.The above reliability tests are based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experimental was taken under good heat dissipation conditions.When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current,voltage distribution,heat dissipation and others. 以上可靠性测试是基于瑞丰现有试验平台颗/条 LED 在良好散热条件验证下的结果，客户端将 LED 应用于串、并联线路时，需自行评估电流、电压分配、散热等问题。

3.The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. [illegible]为参考，不作为任何应用条件及应用方式的保证。

3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1SMT Reflow Soldering Instructions SMT 回流焊说明

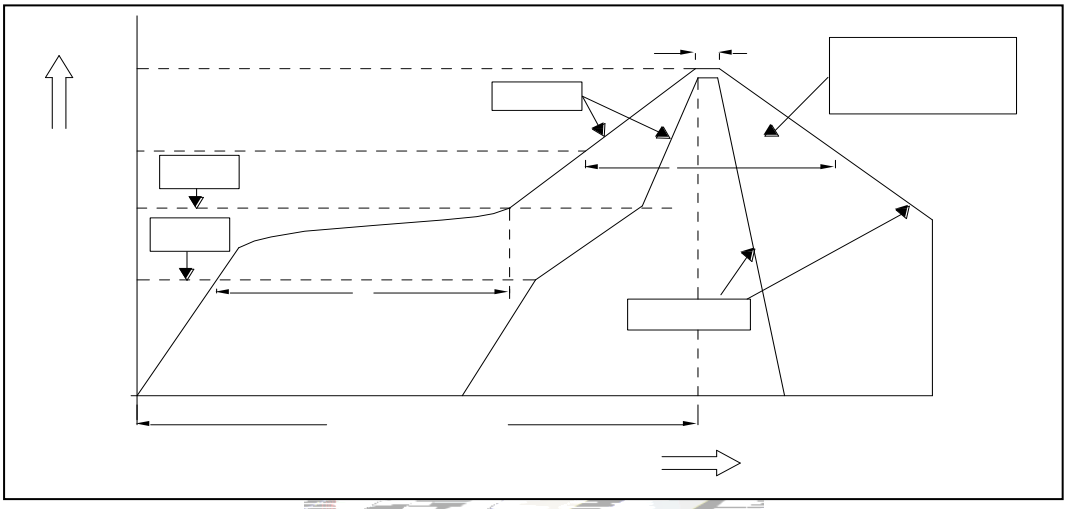


Fig.3-1 SMT Reflow Soldering Instructions SMT 回流焊说明

Table 3-1 SMT Reflow Soldering parameters SMT 回流焊参数

Average temperature rise speed平均升温速度（Tsmax至T_P）	最高3°C/秒 Max 3 °C/ s
Preheating: minimum temperature预热：最低温度（Tsmin)	150 °C
Preheating: Max temperature预热：最高温度（Tsmax)	200 °C
Preheating: Time预热：时间（Tsmin 至Tsmax）	60 - 120秒 60s-120s
Time limited to maintain high temperature: the temperature限时维持高温：温度（T_L)	217 °C
Time limited to maintain high temperature: The Time 限时维持高温：时间（t_L)	最多60秒 Max 60s
Peak /Classification of temperature:峰值 / 分类温度（T_P)	260 °C
Time limit classification of peak temperature time限时峰值分类温度：时间（t_p）	最多10秒 Max 10s
与实际峰值温度（T_P）相差 5 °C 以内的保持时间 Hold time within 5 °C with the actual peak temperature (TP)	最多30秒 Max 30s

降温速度　　Cooling speed	最高6 °C/秒 Max 6 °C/ s
25 °C 升至峰值温度所需时间　　Needed time from 25 °C to Tp	最多8分钟 Max 8minutes

Notes 备注:

(1)Reflow soldering should not be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged. 回流焊次数不可以超过两次，两次回流焊的时间间隔如果超过24小时，LED可能由于吸湿而损坏。

(2)Whensoldering , do not put stress on the LEDs during heating.当焊接时，不要在材料受热时用力压胶体表面。

3.1.1 Soldering Iron 烙铁焊接

(1) When hand soldering, keep the temperature of iron below less 300℃ less than 3 seconds 当手工焊接时，烙铁的温度必须小于300℃，时间不可超过3秒。

(2) The hand solder should be done only one time.手工焊接只可焊接一次。

3.1.2 Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED已焊接后不应该维修，必须维修时，必须使用双头烙铁（如下图），并事先确认此举不会对LED会损坏LED本身的特性。

3.1.3 Cautions 注意事项

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when usethe picking up nozzle, the pressure on the silicone resin should be proper. LED封装胶为硅胶，

表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在按压器件，当使用吸嘴时，胶体表面的压力应是恰当的。

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.回流焊之后冷却过程中，不要对材料实加外力，也不要有震动，回流焊后，不要采用激剧冷却的方式。

4. Handling Precautions 产品使用注意事项

4.1 Handling Precautions 产品使用注意事项

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LEDmating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM.这只是一个建议，不作任何品质担保。

(2) In order to prevent ex- ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.为了防止外界物质进入 LED 内部以造成 LED 的损伤，所处环境及所用套件等等，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议，不作任何品质担保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against theuse of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verifycompatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended tobe used. Attaching LEDs, do not use

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust，requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意，当对产品清洁度要求较高时，回流焊以后需要采用恰当的清洗方式。我们推荐用异丙醇作清洗剂。如需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对 LED 带来损害，不推荐这种清洗方式。

Table 4-1Storage 储存

Conditions 种类		Temperature 温度	Humidity 湿度	Time 时间
Storage	Before Opening Aluminum Bag 拆包前	≤30℃	≤75%	Within 1 Year From Date 一年内
	After Opening Aluminum Bag 拆包后	≤30℃	≤60%	24hours 24小时
Baking 烘烤		60±5℃	-	≥24hours 大于24小时

(8) If the moisture absorbent material（silica gel）has faded away or the LEDs have exceeded the storage time，baking treatment should be performed after unpacking and based on the following condition（60±5）℃ for above 24 hours.如果干燥剂或包装失效，或者产品不符合以上有效储存条件，需拆包后进行烘烤，烘烤条件：60±5℃，大于 24 小时。

If the package is flatulence or damaged,please notify the sales staff to assist.如果包装胀气或者破

(9)Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 像其他的半导体电子器件一样，LED 对静电过流击穿非常敏感，需要做好防护。

(10) Other points for attention, please refer to our relevant information.其它注意事项请参照瑞丰相关资料。

Version History/修订历史

Date日期	Revisor修订者	Version版本	Verifier审核	Remarks备注
2021-02-22		E/0		

Declare 申明

This specification is written both in English and in Chinese and the latter is formal.

产品规格书以中英文方式书写，若有冲突以中文版本为准。